





**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT I - PCN # : A1902-01**

**PCN Type:** Manufacturing Site - Alternate Assembly Location & Alternate material sets  
**Data Sheet Change:** None  
 No change in moisture sensitivity level (MSL)

**Detail Of Change:**

This notification is to advise our customers that IDT is adding ASECL as an alternate assembly and add UMTC as alternate substrate at the existing assembly STATS ChipPAC Korea (SCK).

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	<b>Existing Assembly (ASEK, Taiwan)</b>	<b>Existing Assembly (SCK, Korea)</b>	<b>Alternate Assembly (ASECL, Taiwan)</b>	<b>Alternate Substrate (SCK, Korea)</b>
Die Bump	Cu/Ni/SnAg1.8 (40/3/27um)	Cu/Ni/SnAg1.8 (40/3/27um)	Cu/Ni/SnAg1.8 (40/3/27um)	Cu/Ni/SnAg1.8 (40/3/27um)
Mold Compound	EME-G311A Type C	KEG-1250FC-K	EME-G311A Type C	KEG-1250FC-K
Substrate	UMTC HL832NS/AUS410	Kinsus HL832NS/AUS410	UMTC HL832NS/AUS410	UMTC HL832NS/AUS410
Solder Balls	Sn/Ag1.2/Cu0.50/Ni0.05	Sn/Ag1.2/Cu0.50/Ni0.05	Sn/Ag1.2/Cu0.50/Ni0.05	Sn/Ag1.2/Cu0.50/Ni0.05



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

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**Qualification Information and Qualification Data:**

**Affected Packages:** FCCSP-53

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** FCCSP-53

**(I) ASECL, Taiwan**

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A108	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

\* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

**(II) SCK, Korea**

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A108	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

\* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test